

Description

The ICS408 is a cost-effective clock synthesizer developed to minimize component count for PC peripheral applications. The device supports a common, low cost 14.31818 MHz crystal using an on-chip crystal oscillator. The device locks all output frequencies to enhance system performance. By supporting common PC peripheral interface frequencies of 25MHz, 24.576 MHz, and 40/80 MHz, the ICS408 lowers chip count, reducing system cost and improving reliability.

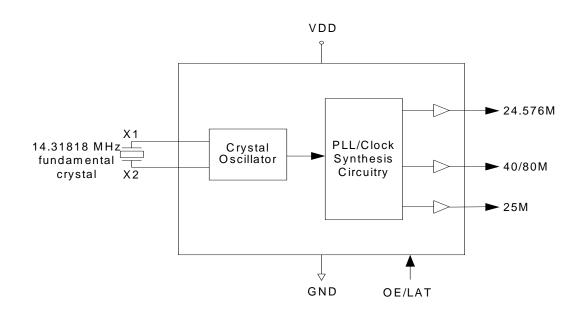
The ICS408 utilizes a low pin count 8-pin SOIC package to optimize board space.

ICS is a leader in low jitter and low power consumer application clock sources. These devices are capable of supporting CCD, video, audio, USB, CPU, and other peripherals.

Block Diagram

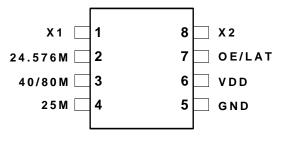
Features

- Low operating voltage of 3.3V
- On-chip oscillator supports 14.31818 MHz crystal
- Fixed 24.576 MHz clock
- Fixed 25MHz clock
- 40/80 MHz selected on rising edge of OE/LAT pin
- Power consumption of 15 mA (typ) extends battery life
- Duty cycle of 45 to 55%
- Packaged in 8 pin SOIC
- Contact ICS for custom frequency requirements





Pin Assignment



8 Pin (150 mil) SOIC

40/80M Frequency Selection

At Power Up	Pin 3* (40/80)
0	40M
1	80M

^{*} Frequency after power up

Pin Descriptions

Pin Number	Pin Name	Pin Type	Pin Description
1	X1	Input	Crystal connection. Connect to 14.31818 MHz parallel mode crystal.
2	24.576M	Output	24.576 MHz clock output. Tri-state when OE/LAT is low.
3	40/80M	Input/ Output	40M or 80M selectable clock output. Latched on rising edge of OE/LAT. Tri-state when OE/LAT is low.
4	25M	Output	25 MHz clock output.
5	GND	Power	Connect to ground.
6	VDD	Power	Connect to voltage supply.
7	OE/LAT	Input	Disables or latches 40/80 MHz output.
8	X2	Input	Crystal connection. Connect to 14.31818 MHz parallel mode crystal.

External Components

Series Termination Resistor

Clock output traces over one inch should use series termination. To series terminate a 50Ω trace (a commonly used trace impedance), place a 33Ω resistor in series with the clock line, as close to the clock output pin as possible. The nominal impedance of the clock output is 20Ω .

Decoupling Capacitor

As with any high performance mixed-signal IC, the ICS408 must be isolated from system power supply noise to perform optimally.

A decoupling capacitor of $0.01\mu F$ must be connected between VDD and the PCB ground plane.

Crystal Load Capacitors

The device crystal connections should include pads for small capacitors from X1 to ground and from X2 to ground. These capacitors are used to adjust the stray capacitance of the board to match the nominally required crystal load capacitance. Because load capacitance can only be increased in this trimming process, it is important to keep stray capacitance to a minimum by using very short PCB traces (and no vias)



been the crystal and device. Crystal capacitors must be connected from each of the pins X1 and X1 to ground.

The value (in pF) of these crystal caps should equal $(C_L -6pF)^*2$. In this equation, $C_L =$ crystal load capacitance in pF. Example: For a crystal with a 15 pF load capacitance, each crystal capacitor would be 18 pF [(15-6) x 2] = 18.

PCB Layout Recommendations

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

1) The 0.01µF decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between the decoupling capacitor and VDD pin. The PCB trace

- to VDD pin should be kept as short as possible, as should the PCB trace to the ground via.
- 2) The external crystal should be mounted just next to the device with short traces. The X1 and X2 traces should not be routed next to each other with minimum spaces, instead they should be separated and away from other traces.
- 3) To minimize EMI the 33Ω series termination resistor, if needed, should be placed close to the clock output.
- 4) An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers. Other signal traces should be routed away from the ICS408. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

Selection of 40M/80M Clock

The 40/80M output clock is selected by a soft pull-upp or pull-down on 40/80M pin (pin 3). On power up, the rising edge on OE latches, in the high or low level, on pin 3 which starts the appropriate frequency. Any low-to-high transistion on OE/LAT after power up will latch the logic level on pin 3.



Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the ICS408. These ratings, which are standard values for ICS commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	7 V
All Inputs and Outputs	-0.5 V to VDD+0.5 V
Ambient Operating Temperature	0 to +70 °C
Storage Temperature	-65 to +150 °C
Junction Temperature	175 °C
Soldering Temperature	260 °C

Recommended Operation Conditions

Parameter	Min.	Тур.	Max.	Units
Ambient Operating Temperature	0	_	+70	°C
Power Supply Voltage (measured in respect to GND)	+3.00		+3.60	V

DC Electrical Characteristics

VDD=3.3V ±10%

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		3.0		3.6	V
Input High Voltage	V _{IH}		VDD-0.5			V
Input Low Voltage	V _{IL}				0.5	V
Output High Voltage	V _{OH}	I _{OH} = -20 mA	2.4			V
Output Low Voltage	V _{OL}	I _{OL} = 20 mA			0.8	V
Operating Supply Current	IDD	No load on outputs		15		mA
Short Circuit Current	Ios	Each output		60		mA



AC Electrical Characteristics

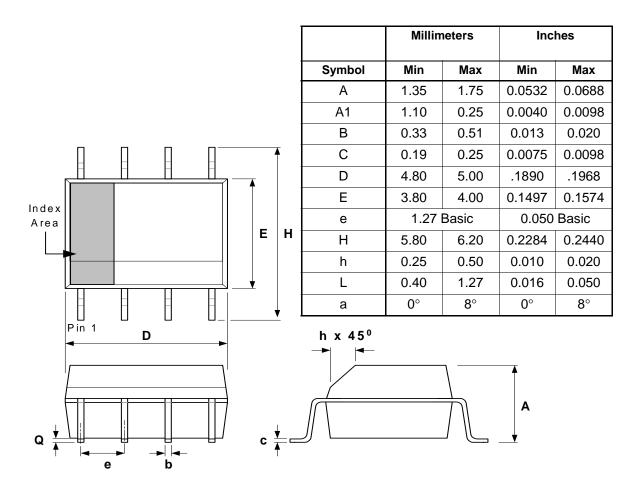
VDD = 3.3V \pm 10\%, Ambient Temperature 0 to $+70 \times$ C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency				14.318		MHz
Output Rise Time	t _{OR}	0.8 to 2.0 V, C _L =15 pF		0.8		ns
Output Fall Time	t _{OF}	2.0 to 0.8 V, C _L =15 pF		0.6		ns
Output Clock Duty Cycle		at VDD/2	45	50	55	%
Absolute Jitter, Short Term		variation from mean		<u>+</u> 250		ps



Package Outline and Package Dimensions (8 pin SOIC, 150 Mil. Narrow Body)

Package dimensions are kept current with JEDEC Publication No. 95



Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
ICS408M	ICS408	Tubes	8 pin SOIC	0 to 70 °C
ICS408MT	ICS408	Tape and Reel	8 pin SOIC	0 to 70 °C

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